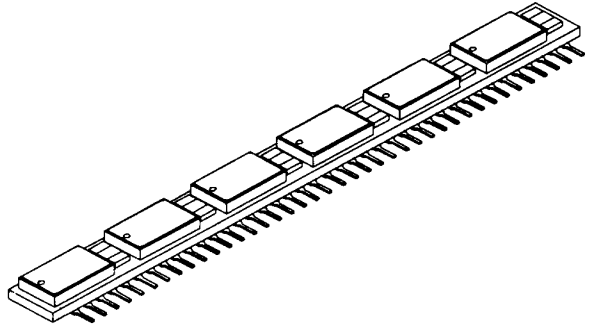


**NOT RECOMMENDED FOR NEW DESIGNS**

**DESCRIPTION:**

The DPS384 is a 64K X 6 high-speed, low-power static RAM module comprised of six 64K X 1 monolithic SRAM's, and decoupling capacitors surface mounted on a single inline co-fired ceramic substrate.

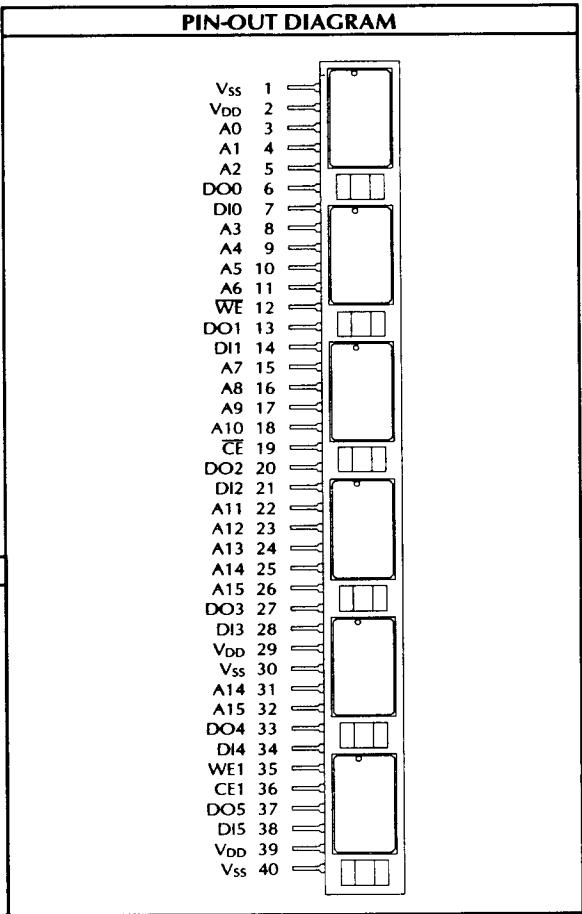
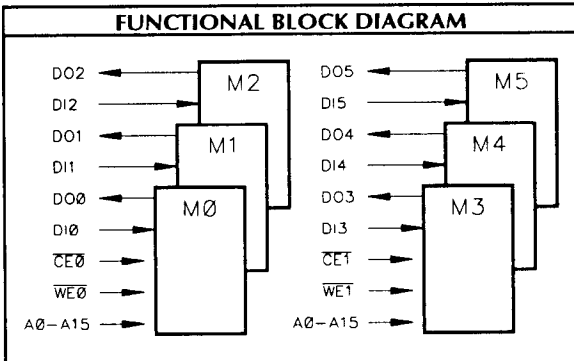
The DPS384 operates from a single +5V supply and all input and output pins are completely TTL-compatible. The DPS384 is best suited for high speed military computers and signal processing applications.



**FEATURES:**

- Organizations Available: 64K X 6 or 128K X 3
- Access Times: 15, 25, 35, 45, 55ns (max.)
- Low Power Dissipation
- Completely Static Operation - No Clock or Refresh Needed
- Three State Output
- All Inputs and Outputs are TTL-Compatible
- 40-Pin SIP

PIN NAMES	
A0 - A15	Address Inputs
DI0 - DI5	Data Inputs
DO0 - DO5	Data Outputs
CE0 / CE1	Chip Enables
WE0 / WE1	Write Enables
VDD	Power (+5V)
VSS	Ground



**NOT RECOMMENDED FOR NEW DESIGNS**

RECOMMENDED OPERATING RANGE <sup>1</sup>					
Symbol	Characteristic	Min.	Typ.	Max.	Unit
V <sub>DD</sub>	Supply Voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	Input HIGH Voltage	2.2		V <sub>DD</sub> +0.5	V
V <sub>IL</sub>	Input LOW Voltage	-0.5 <sup>2</sup>		0.8	V

CAPACITANCE <sup>4</sup> : T <sub>A</sub> = 25°C, F = 1.0MHz				
Symbol	Parameter	Max.	Unit	Condition
C <sub>ADR</sub>	Address Input	70	pF	V <sub>IN</sub> = 0V
C <sub>CE</sub>	Chip Enable	40		
C <sub>WE</sub>	Write Enable	40		
C <sub>I/O</sub>	Data Input/Output	25		

ABSOLUTE MAXIMUM RATINGS <sup>3</sup>			
Symbol	Parameter	Value	Unit
T <sub>STC</sub>	Storage Temperature	-65 to +150	°C
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
V <sub>DD</sub>	Supply Voltage <sup>1</sup>	-0.5 to +7.0	V
V <sub>I/O</sub>	Input/Output Voltage <sup>1</sup>	-0.5 to V <sub>DD</sub> + 0.5	V

TRUTH TABLE				
Mode	CE	WE	I/O Pin	Supply Current
Not Selected	H	X	HIGH-Z	Standby
Read	L	H	DOUT	Active
Write	L	L	DIN	Active

H=HIGH                      L=LOW                      X=Don't Care

DC OPERATING CHARACTERISTICS: Over operating ranges							
Symbol	Characteristics	Test Conditions	X3		X6		Unit
			Min.	Max.	Min.	Max.	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 0V to V <sub>DD</sub>	-60	+60	-60	+60	μA
I <sub>OUT</sub>	Output Leakage Current	V <sub>I/O</sub> = 0V to V <sub>DD</sub> , CE or OE = V <sub>IH</sub> , or WE = V <sub>IL</sub>	-20	+20	-10	+10	μA
I <sub>CC1</sub>	Operating Power Supply Current	CE = V <sub>IL</sub> , f = 0 Outputs Open		480		630	mA
I <sub>CC2</sub>	Dynamic Operating Supply Current	Outputs Open CE = V <sub>IL</sub> , f = max.		615		840	mA
I <sub>SB1</sub>	Standby Supply Current (TTL)	CE = V <sub>IH</sub>		330		330	mA
I <sub>SB2</sub>	Full Standby Supply Current (CMOS)	CE ≥ V <sub>DD</sub> - 0.2V, V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2V or V <sub>IN</sub> ≤ V <sub>SS</sub> + 0.2V		150		150	mA
V <sub>OL</sub>	Output Low Voltage	V <sub>OL</sub> = 8.0mA		0.4		0.4	V
V <sub>OH</sub>	Output High Voltage	V <sub>OH</sub> = -4.0mA	2.4		2.4		V

NOTE: Dense-Pac has other specialized suppliers that may provide better A.C. or D.C. Characteristics.

NOT RECOMMENDED FOR NEW DESIGNS

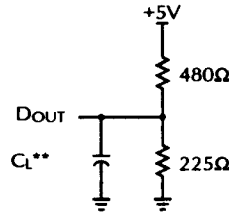
AC TEST CONDITIONS	
Input Pulse Levels	0V to 3.0V
Input Pulse Rise and Fall Times	5ns*
Input and Output Timing Reference Levels	1.5V

\* Transient between 0.8V and 2.2V.

Output Load		
Load	C <sub>L</sub>	Parameters Measured
1	30 pF	except t <sub>CLZ</sub> , t <sub>CHZ</sub> , t <sub>WHZ</sub> , and t <sub>WLZ</sub>
2	5 pF	t <sub>CLZ</sub> , t <sub>CHZ</sub> , t <sub>WHZ</sub> , and t <sub>WLZ</sub>

Figure 1. Output Load

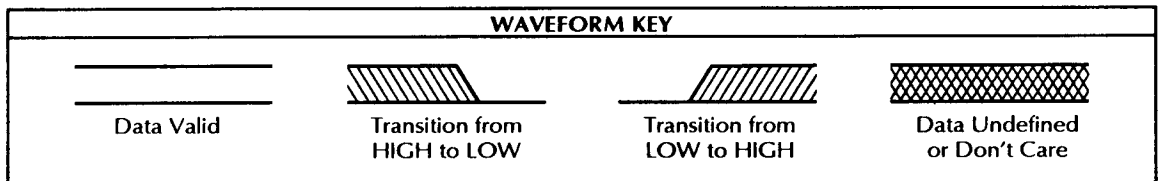
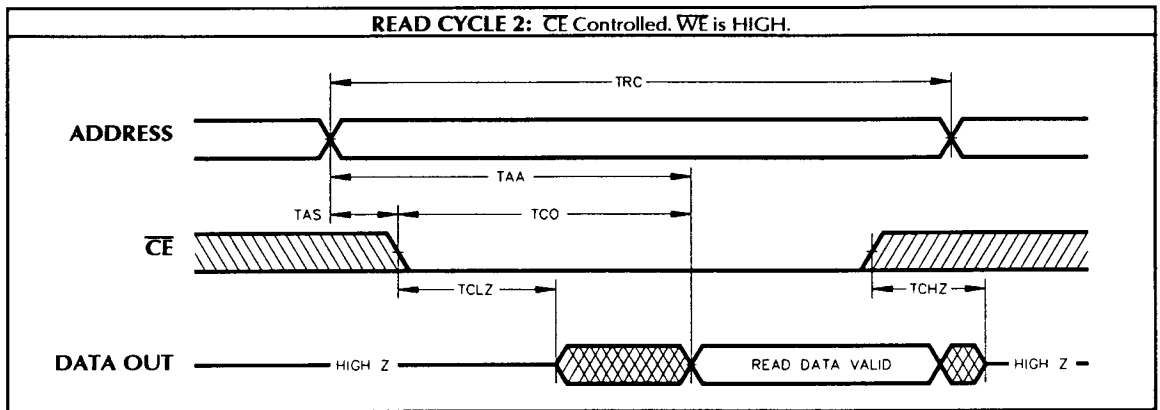
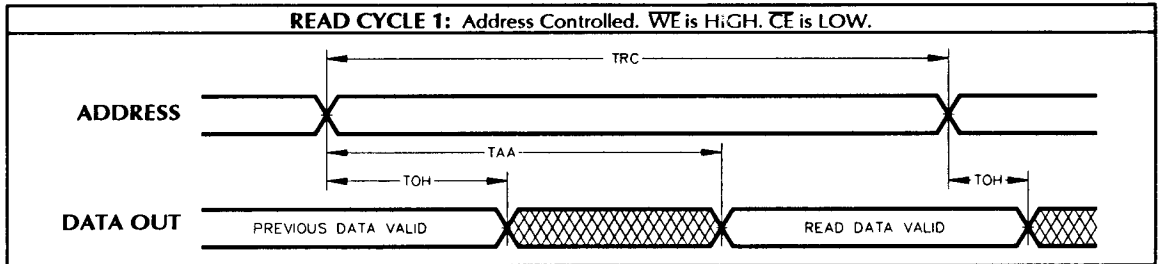
\*\* Including Probe and Jig Capacitance.



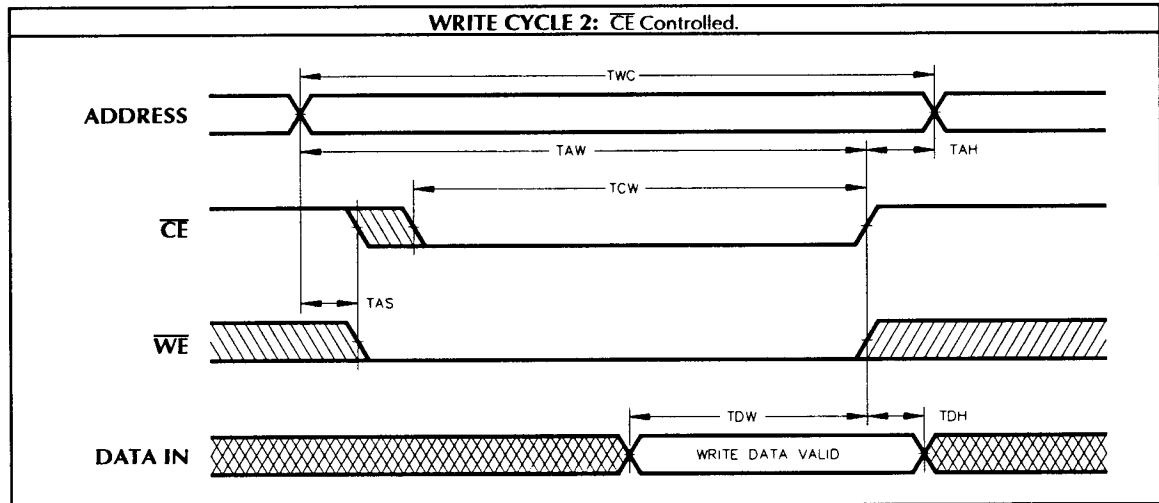
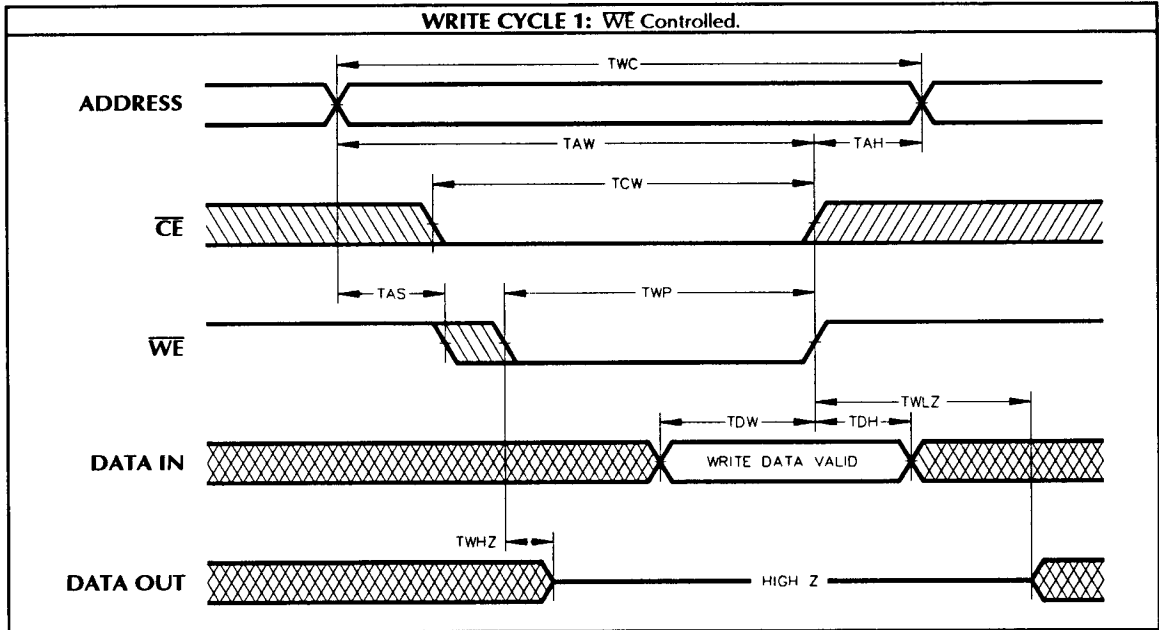
AC OPERATING CONDITIONS AND CHARACTERISTICS - READ CYCLE: Over operating ranges <sup>6</sup>													
No.	Symbol	Parameter	-15		-25		-35		-45		-55		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
1	t <sub>RC</sub>	Read Cycle Time	15		25		35		45		55		ns
2	t <sub>AA</sub>	Address Access Time		15		25		35		45		55	ns
3	t <sub>CO</sub>	Chip Enable to Output Valid		15		25		35		45		55	ns
4	t <sub>OH</sub>	Output Hold for Address Change	5		5		5		5		5		ns
5	t <sub>CLZ</sub>	Chip Enable to Output in LOW-Z <sup>4, 5</sup>	5		5		5		5		5		ns
6	t <sub>CHZ</sub>	Chip Enable to Output in HIGH-Z <sup>4, 5</sup>		8		15		20		35		35	ns

AC OPERATING CONDITIONS AND CHARACTERISTICS - WRITE CYCLE: Over operating ranges <sup>7</sup>													
No.	Symbol	Parameter	-15		-25		-35		-45		-55		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
10	t <sub>WC</sub>	Write Cycle Time	15		25		35		45		55		ns
11	t <sub>AW</sub>	Address Valid to End of Write	12		20		30		40		50		ns
12	t <sub>CW</sub>	Chip Enable to End of Write	12		20		30		40		50		ns
13	t <sub>DW</sub>	Data Valid to End of Write	14		25		25		25		25		ns
14	t <sub>DH</sub>	Data Hold Time	0		0		0		0		0		ns
15	t <sub>WP</sub>	Write Pulse Width	10		15		20		25		35		ns
16	t <sub>AS</sub>	Address Set-up Time***	5		5		5		5		5		ns
17	t <sub>AH</sub>	Address Hold Time	5		5		5		5		5		ns
18	t <sub>WHZ</sub>	Write Enable to Output in HIGH-Z <sup>4, 5</sup>		15		20		20		25		25	ns
19	t <sub>WLZ</sub>	Write Enable to Output in LOW-Z <sup>4, 5</sup>	5		5		5		5		5		ns

\*\*\* Valid for both Read and Write Cycles.

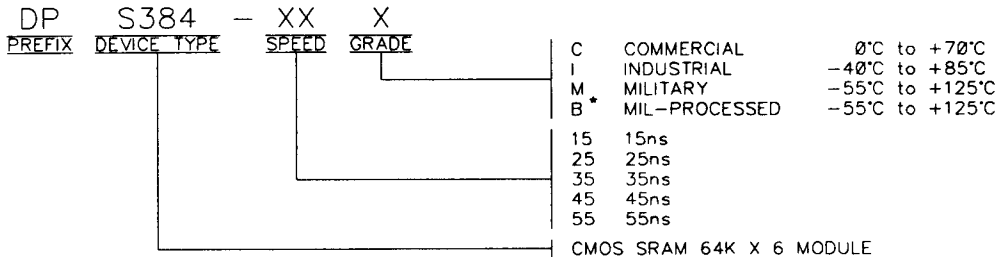


NOT RECOMMENDED FOR NEW DESIGNS



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### ORDERING INFORMATION

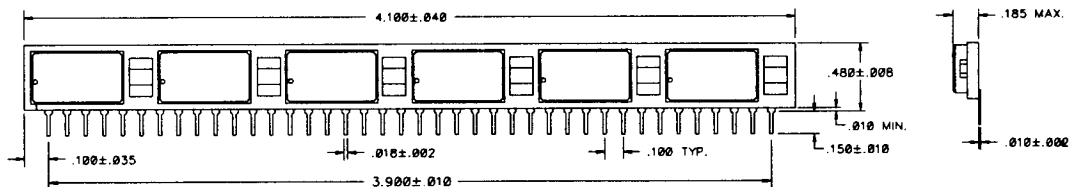


\* B grade modules built with 883 devices.

### NOTES:

1. All voltages are with respect to  $V_{SS}$ .
2. -3.0V min. for pulse width less than 20ns ( $V_{IL}$  min. = -0.5V at DC level).
3. Stresses greater than those under **ABSOLUTE MAXIMUM RATINGS** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
4. This parameter is guaranteed and not 100% tested.
5. Transition is measured at the point of  $\pm 500mV$  from steady state voltage.
6. When  $\overline{CE}$  is LOW and  $\overline{WE}$  is HIGH, I/O pins are in the output state, and input signals of opposite phase to the outputs must not be applied.
7. The outputs are in a high impedance state when  $\overline{WE}$  is LOW.

### MECHANICAL DRAWING



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